# **Specification of Thermoelectric Module**

TEC1-12707S

### **Description**

The 127 couples, 62 mm × 62 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

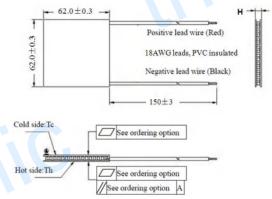
### **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	16	17.2	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	6.6	6.6	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	66.2	72.3	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.85	2.0	The module resistance is tested under AC
Tolerance (%)	4	10	For thermal and electricity parameters

#### Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)
Sullix	(mm)	Parallelism (mm)	Standard/Optional length
TF	0:6.1±0.1	0:0.12/0.12	150±3/Specify
TF	1:6.1±0.05	1:0.06/0.06	150±3/Specify

Eg. TF00: Thickness  $6.1 \pm 0.1$  (mm) and Flatness 0.12 / 0.12 (mm)

# **Manufacturing Options**

Δ	Sal	lder:	

#### **B. Sealant:**

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

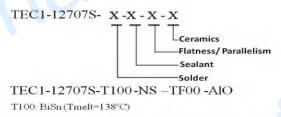
#### C. Ceramics:

#### **D. Ceramics Surface Options:**

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

## Naming for the Module



NS: No sealing

AlO: Alumina (Al2O3, white 96%)

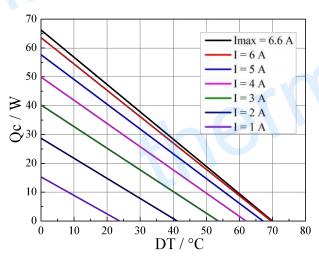
TF00: Thickness ±0.1(mm) and Flatness/Parallelism:0.05/0.05(mm)

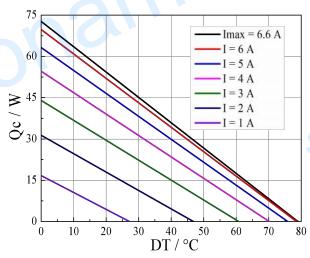
# **Specification of Thermoelectric Module**

### **TEC1-12707S**

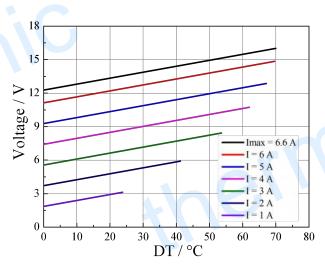
### Performance Curves at Th=27 °C

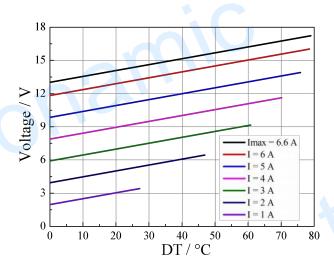
### Performance Curves at Th=50 °C



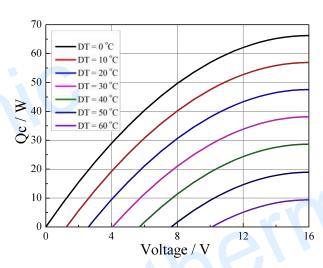


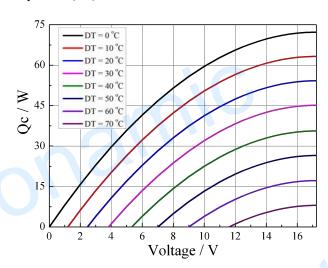
Standard Performance Graph Qc= f(DT)





Standard Performance Graph  $V = f(\Delta T)$ 





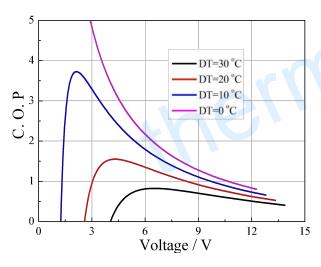
Standard Performance Graph Qc = f(V)

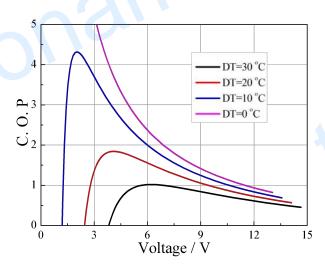
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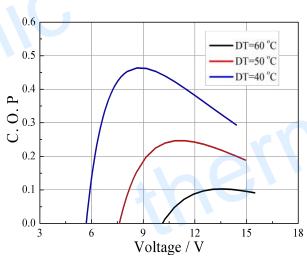
### Performance Curves at Th=27 °C

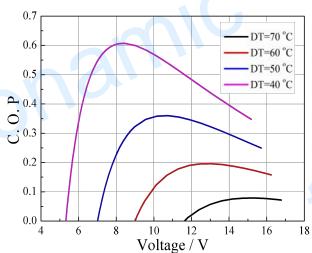
### Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

### **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC